

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc2966hsw#pbf

(Engineering Calculation)

SOIC WIDE

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**TOTAL MASS (g) : 0.537848**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001460	1000000	2714.52319336		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.153163	975000	284770.21875		
		Iron (Fe)	7439-89-6	0.003770	24000	7009.41894531		
		Phosphorus (P)	7723-14-0	0.000047	300	87.3853378296		
		Zinc (Zn)	7440-66-6	0.000110	700	204.518859863		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.157090</b>	<b>1000000</b>	<b>292071.53125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.005974	1000000	11106.6337891		
		<b>External Plating Total:</b>				<b>0.005974</b>	<b>1000000</b>	<b>11106.6337891</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001257	1000000	2337.09277344		
<b>Internal Plating Total:</b>				<b>0.001257</b>	<b>1000000</b>	<b>2337.09277344</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000558	750000	1037.46838379		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000186	250000	345.822814941		
<b>Die Attach Total:</b>				<b>0.000744</b>	<b>1000000</b>	<b>1383.29125977</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.038213	103000	71047.9921875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.332045	895000	617358.75		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000742	2000	1379.57263184		
		<b>Encapsulation Total:</b>				<b>0.371000</b>	<b>1000000</b>	<b>689786.3125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000323	1000000	600.541687012		
					<b>TOTAL MASS (g) :</b>	<b>0.537848</b>		